

WHAT IS CLAIMED IS:

1. An abrasive slurry having high dispersion stability, comprising:

abrasive fine particles made of one or more kinds of oxides;
colloidal fine particles made of colloidal oxide with an average particle size smaller than an average particle size of the abrasive fine particles; and

a dispersion medium in which the abrasive fine particles and the colloidal fine particles are dispersed.

2. An abrasive slurry having high dispersion stability according to claim 1, wherein the average particle size (D_p) of the abrasive fine particles is 100 to 5,000 nm, the average particle size (D_c) of the colloidal fine particles is 10 to 300 nm, and a particle size ratio (D_c/D_p) of the average particle size (D_c) of the colloidal fine particles to the average particle size (D_p) of the abrasive fine particles is 10 or less.

3. An abrasive slurry having high dispersion stability according to claim 1 or 2, wherein the abrasive fine particles have a particle concentration (C_p) of 5 to 30 wt%, the colloidal fine particles have a particle concentration (C_c) of 0.1 to 5 wt%, and a weight distribution ratio (C_c/C_p) of the particle concentration

(Cc) of the colloidal fine particles to the particle concentration (Cp) of the abrasive fine particles is 1 or less.

4. An abrasive slurry having high dispersion stability according to any one of claims 1 to 3, wherein the dispersion medium comprises water or an aqueous dispersion medium mainly containing water.

5. An abrasive slurry having high dispersion stability according to any one of claims 1 to 4, wherein the abrasive fine particles comprise a cerium oxide particle.

6. An abrasive slurry having high dispersion stability according to any one of claims 1 to 5, wherein the colloidal fine particles comprise a colloidal silica.

7. A manufacturing method for a substrate as an inorganic substrate, comprising polishing the substrate using the abrasive slurry according to any one of claims 1 to 6.

8. A manufacturing method for a substrate according to claim 7, wherein the substrate has a surface on which an oxide film is formed.